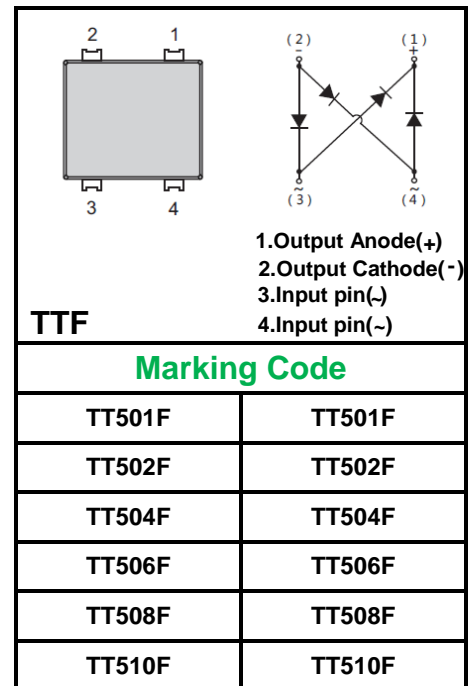


5A SURFACE MOUNT GLASS PASSIVATED BRIDGE
RECTIFIER Reverse Voltage - 100 to 1000 V
Forward Current – 5.0A
FEATURES

- ◆High current capability
- ◆Low forward voltage drop
- ◆Glass Passivated Chip Junction
- ◆Designed for Surface Mount Application
- ◆Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- ◆Case: TTF
- ◆Terminals: Solderable per MIL-STD-750, Method 2026
- ◆Approx. Weight: 0.461g / 0.0163oz


Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	TT501F	TT502F	TT504F	TT506F	TT508F	TT510F	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current	I_o	5.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load(JEDEC method)	I_{FSM}	180						A
I2t Rating for Fusing	I^2t	134						A ² S
Forward Voltage per element at 1.0A	V_F	0.83(TYP)						V
Forward Voltage per element at 5.0A	V_F	1.0						V
Maximum DC Reverse Current @ $T_A=25^{\circ}C$ at Rated DC Blocking Voltage @ $T_A=125^{\circ}C$	I_R	5 100						μA
Typical Junction Capacitance ^(Note1)	C_j	60						pF
Typical Thermal Resistance ^(Note2)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	60 10 12						$^{\circ}C/W$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^{\circ}C$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) Mounted on glass epoxy PC board with 4x1.5"x1.5" (3.81x3.81 cm) copper pad.

Fig.1 Average Rectified Output Current Derating Curve

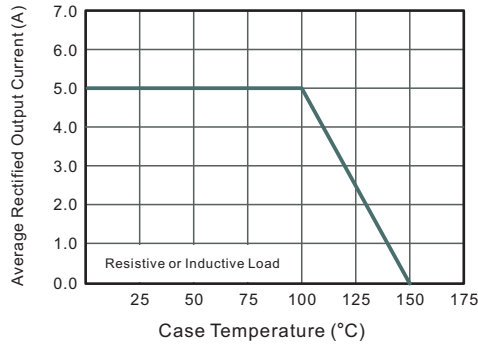


Fig.2 Typical Reverse Characteristics

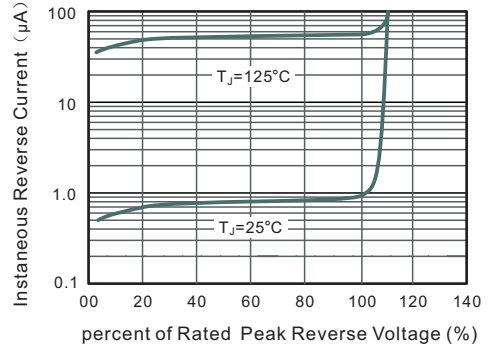


Fig.3 Typical Instantaneous Forward Characteristics

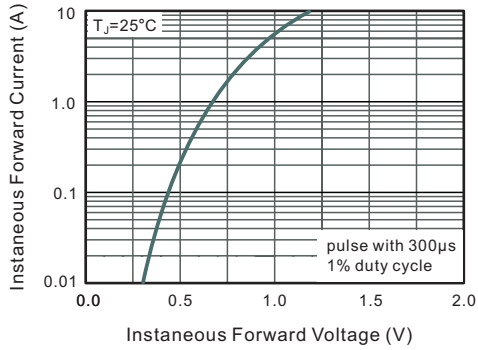


Fig.4 Typical Junction Capacitance

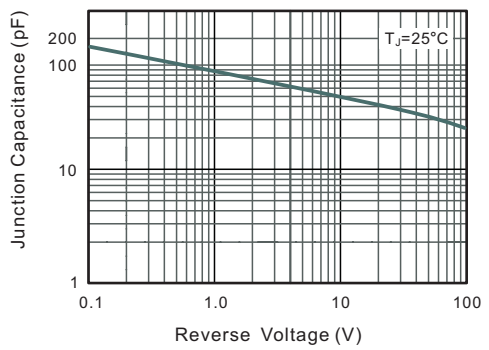


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

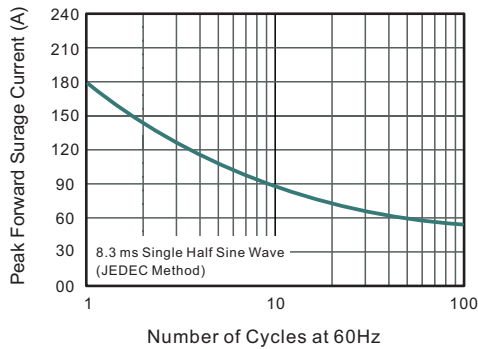
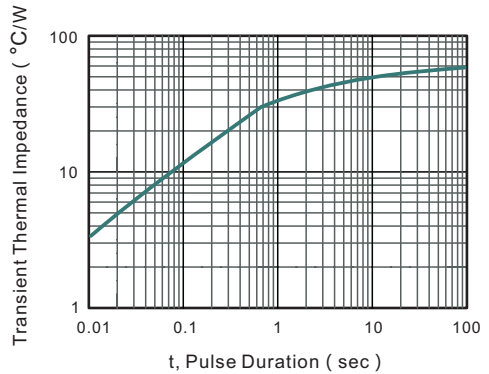
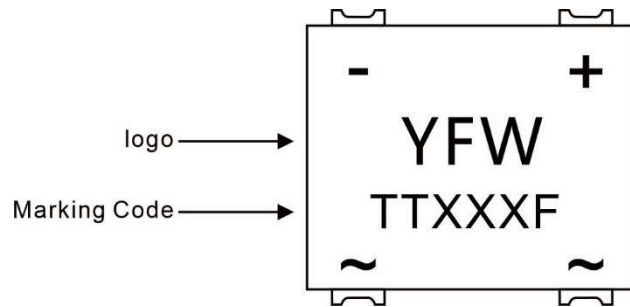


Fig.6- Typical Transient Thermal Impedance



Marking Diagram



Ordering information

Package	Packing Description	Packing Quantity
TTF	Tape/Reel, 13" reel	3000PCS/Reel 30000PCS/Carton

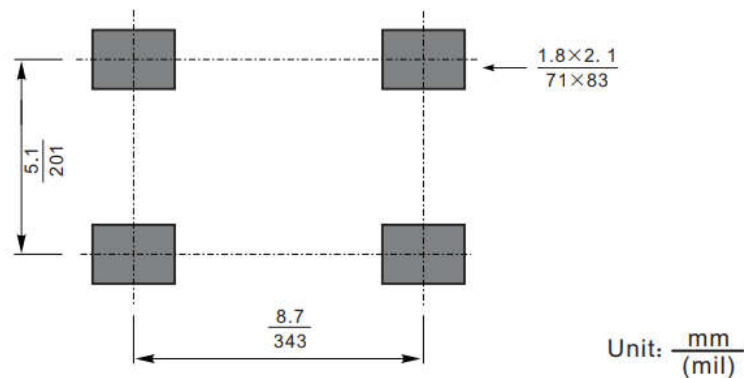
Package Dimensions

TTF

Dim.	Millimeter(mm)		(mil)	
	Min.	Max.	Min.	Max.
A	1.35	1.75	53	68
C	0.25	0.55	9.8	21.6
D	9.4	9.8	370	385
E	8.4	8.8	330	346
E ₁	9.8	10.2	385	401
L	0.85	1.25	33	49
e	4.9	5.3	193	209
b	1.25	1.55	49	61
∠	10°			

The technical drawings include a top view with dimensions E and D, a side view with dimensions L and e, and a detail view of the lead with dimensions C and A. A note 'ALL ROUND' is present near the lead detail. A small symbol is located at the bottom right of the detail view.

The recommended mounting pad size



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